Marubeni

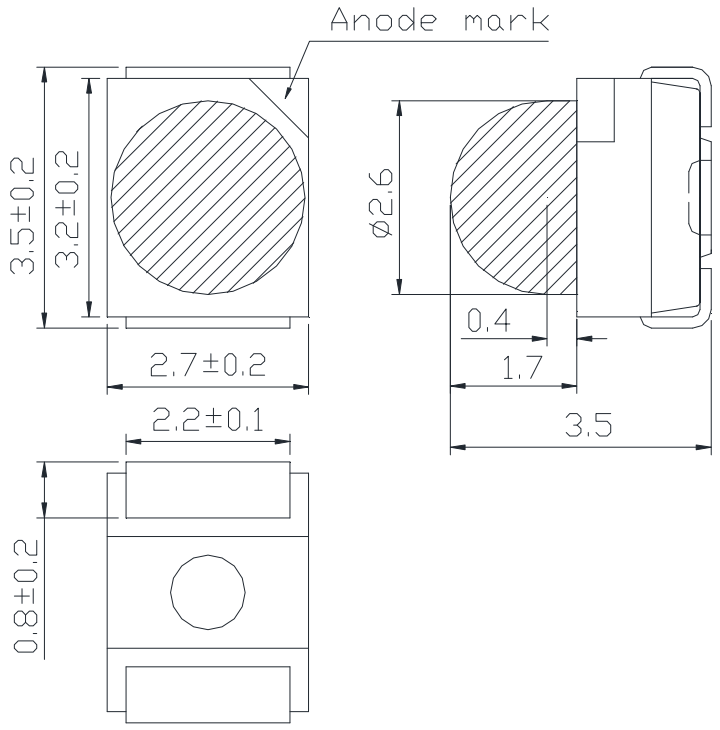
Data Sheet

2020.05

SMT1200D-23

1200nm High Performance Infrared TOP LED

Outline and Internal Circuit



(Unit : mm)

Features

- Chip Material : InGaAsP
- Chip Dimension : 350um * 350um
- Number of Chips : 1pce
- Peak Wavelength : 1200nm typ.
- Lead Frame Die : Silver Plated
- Package Resin : PA6T
- Lens : Silicone or Epoxy Resin

Absolute Maximum Ratings (Tc=25°C)

Item	Symbol	Ratings	Unit
Power Dissipation	PD	140	mW
Forward Current	IF	100	mA
Pulse Forward Current	IFP	1000	mA
Reverse Voltage	VR	5	V
Thermal Resistance	Rthja	80	K/W
Junction Temperature	Tj	120	°C
Operating Temperature	Topr	-40 ~ +100	°C
Storage Temperature	Tstg	-40 ~ +100	°C
Soldering Temperature	TSOL	250	°C

‡Pulse Forward Current condition : Duty 1% and Pulse Width=10us.

‡Soldering condition : Soldering condition must be completed with 5 seconds at 250°C.

Optical and Electrical Characteristics (Tc=25°C)

(*: 100% testing, **: reference value)

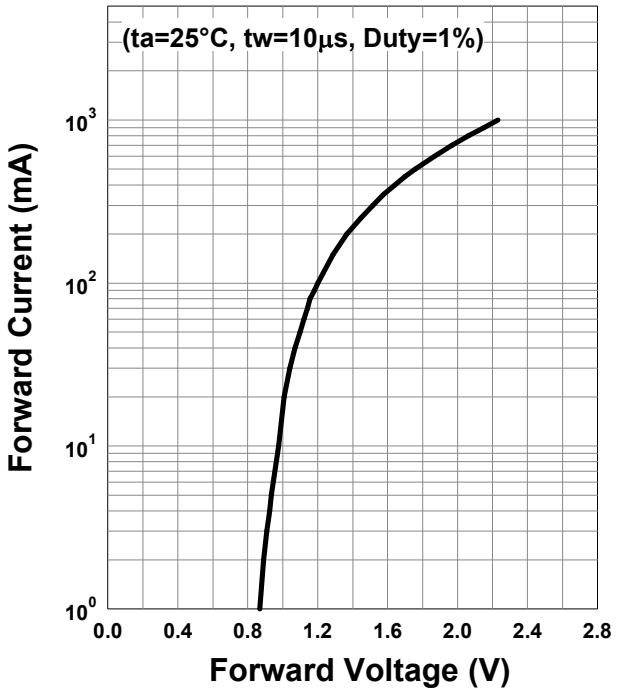
Parameter	Symbol	Min	Typ	Max	Unit	Test Condition
Forward Voltage	VF		1.1	1.4	V	IF=50mA*
	VFP		2.2			IFP=1A**
Reverse Current	IR			10	uA	VR=5V*
Total Radiated Power	PO	6.5	10		mW	IF=50mA*
			64			IFP=1A**
Radiant Intensity	IE		48		mW/sr	IF=50mA**
			310			IFP=1A**
Peak Wavelength	λp	1170		1230	nm	IF=50mA*
Half Width	Δλ		80		nm	IF=50mA**
Viewing Half Angle	θ1/2		±16		deg.	IF=50mA**
Rise Time	tr		60		ns	IF=50mA**
Fall Time	tf		30		ns	IF=50mA**

‡ Radiated Power is measured by G8370-85.

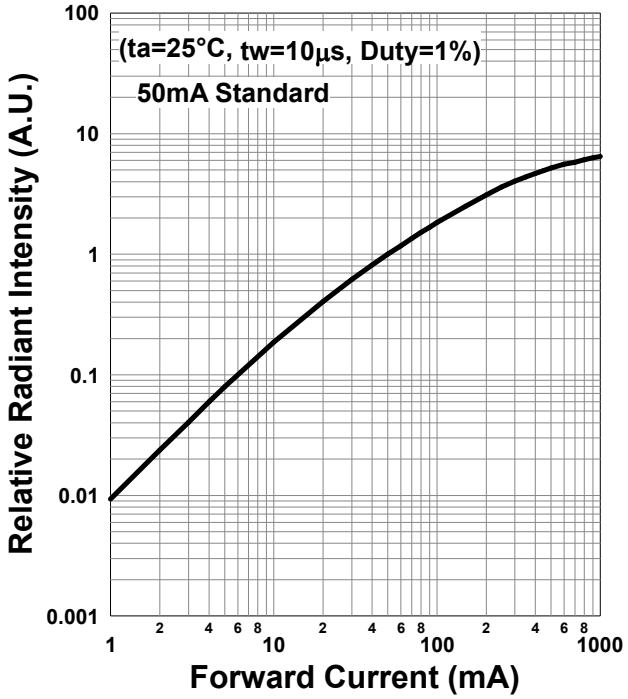
‡ Radiant Intensity is measured by ANDO Optical Multi Meter AQ2140 & AQ2743.

Typical Characteristic Curves

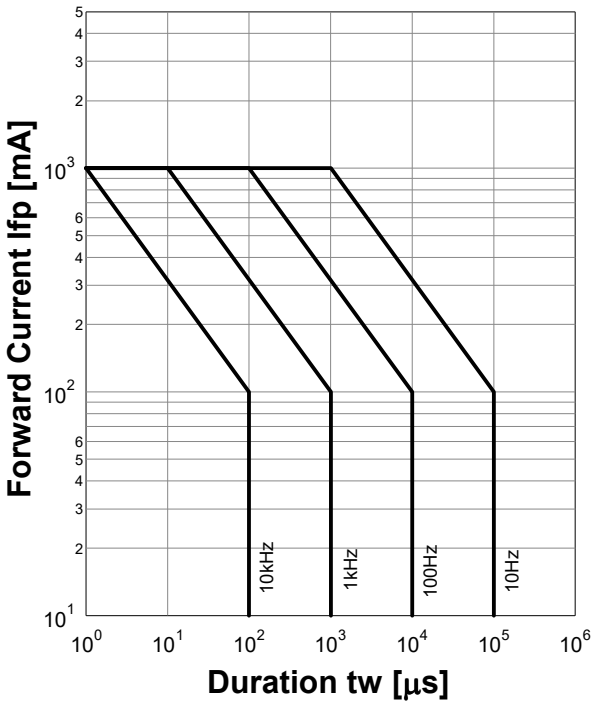
Forward Current - Forward Voltage



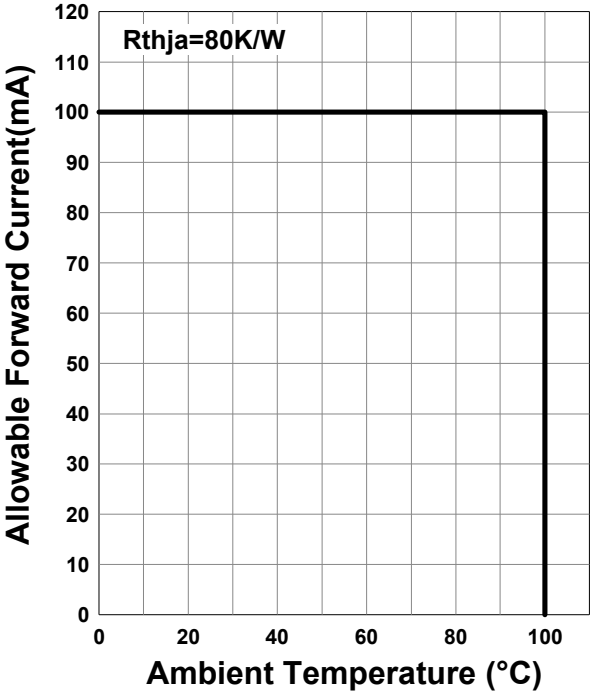
Relative Radiant Intensity - Forward Current

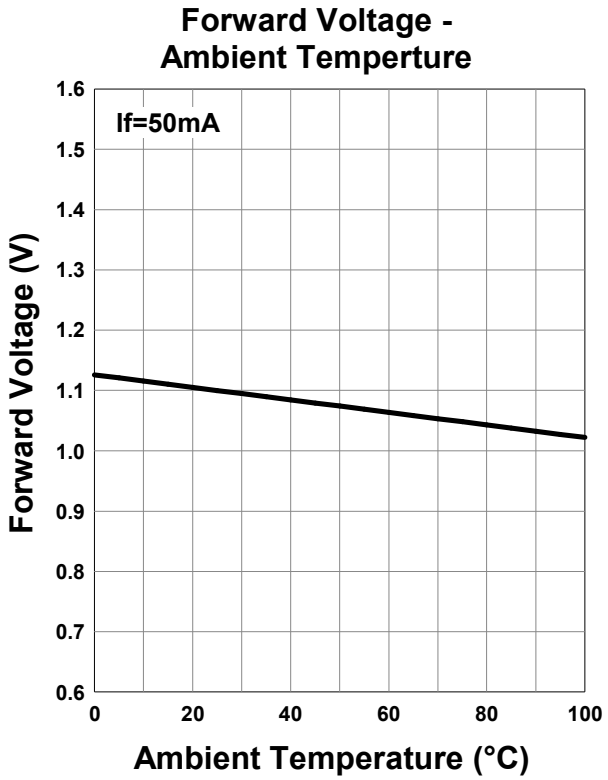


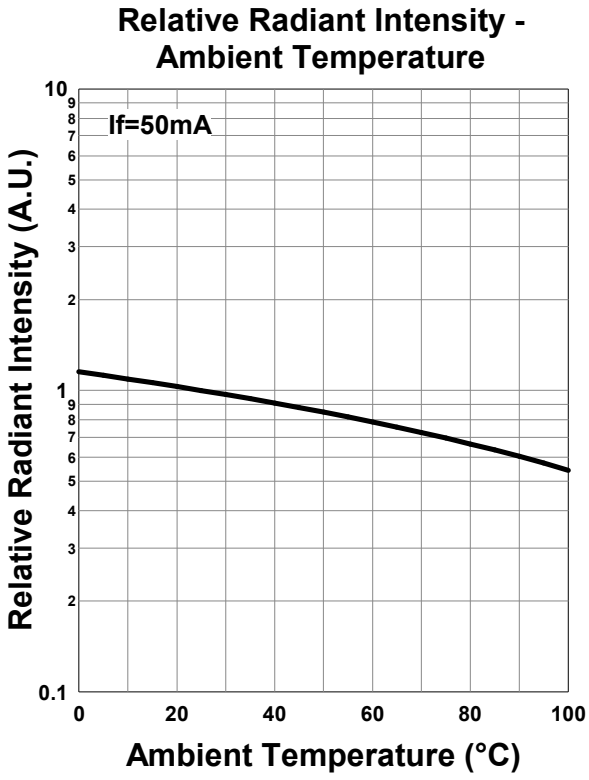
Forward Current - Pulse Duration

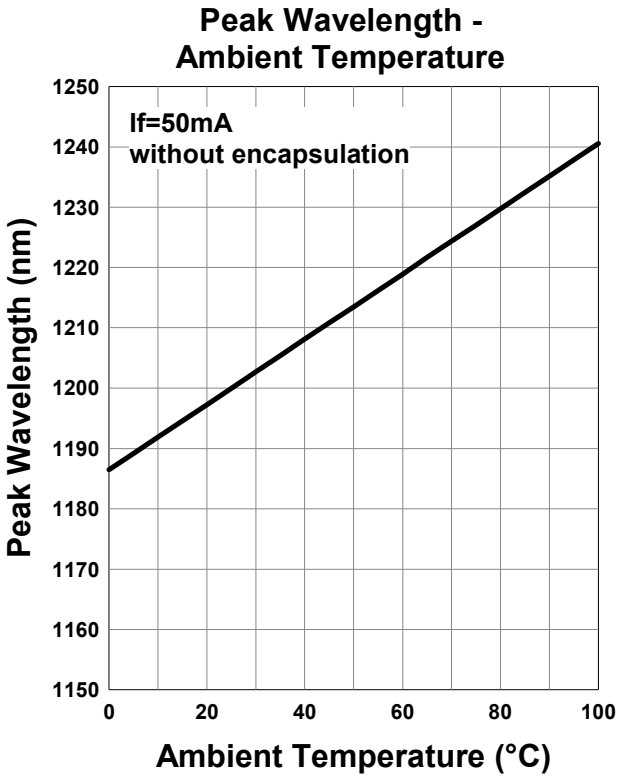


Allowable Forward Current - Ambient Temperature

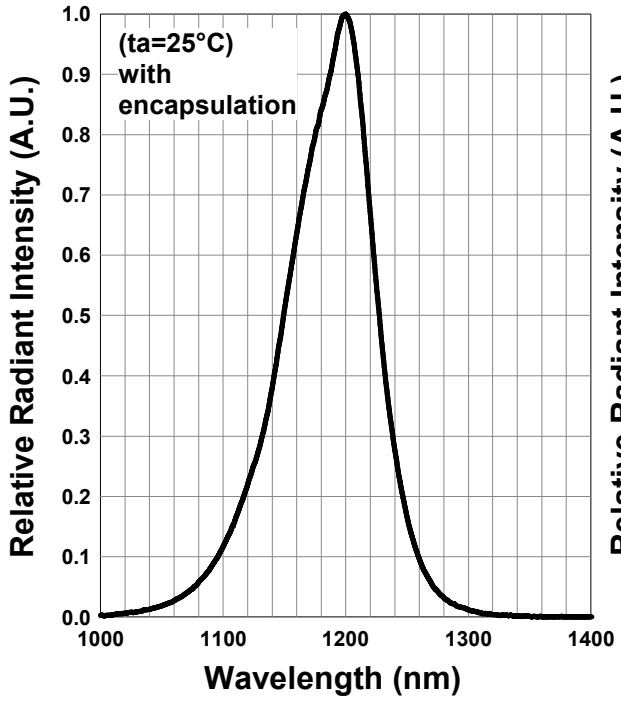



Forward Voltage -
Ambient Temperture
If=50mA
Forward Voltage (V)
1.6
1.5
1.4
1.3
1.2
1.1
1.0
0.9
0.8
0.7
0.6
0
20
40
60
80
100
Ambient Temperature (°C)

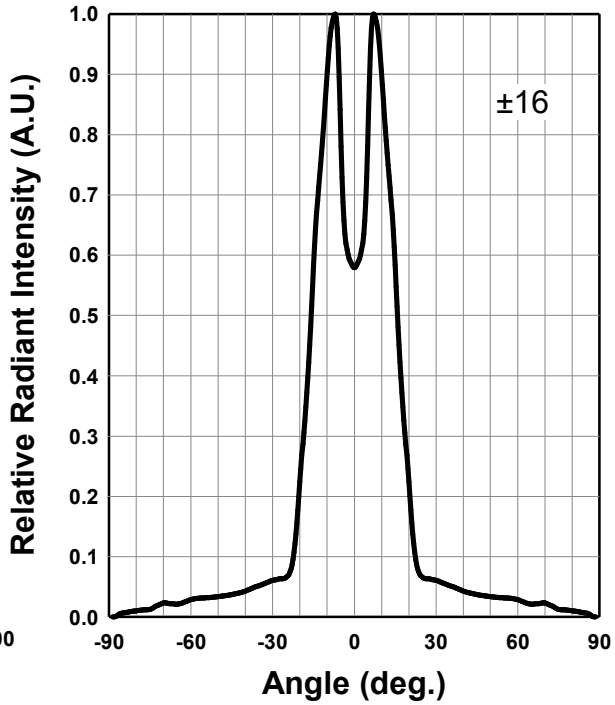

Relative Radiant Intensity -
Ambient Temperature
If=50mA
Relative Radiant Intensity (A.U.)
10
1
0.1
0
20
40
60
80
100
Ambient Temperature (°C)


Peak Wavelength -
Ambient Temperature
If=50mA
without encapsulation
Peak Wavelength (nm)
1250
1240
1230
1220
1210
1200
1190
1180
1170
1160
1150
0
20
40
60
80
100
Ambient Temperature (°C)

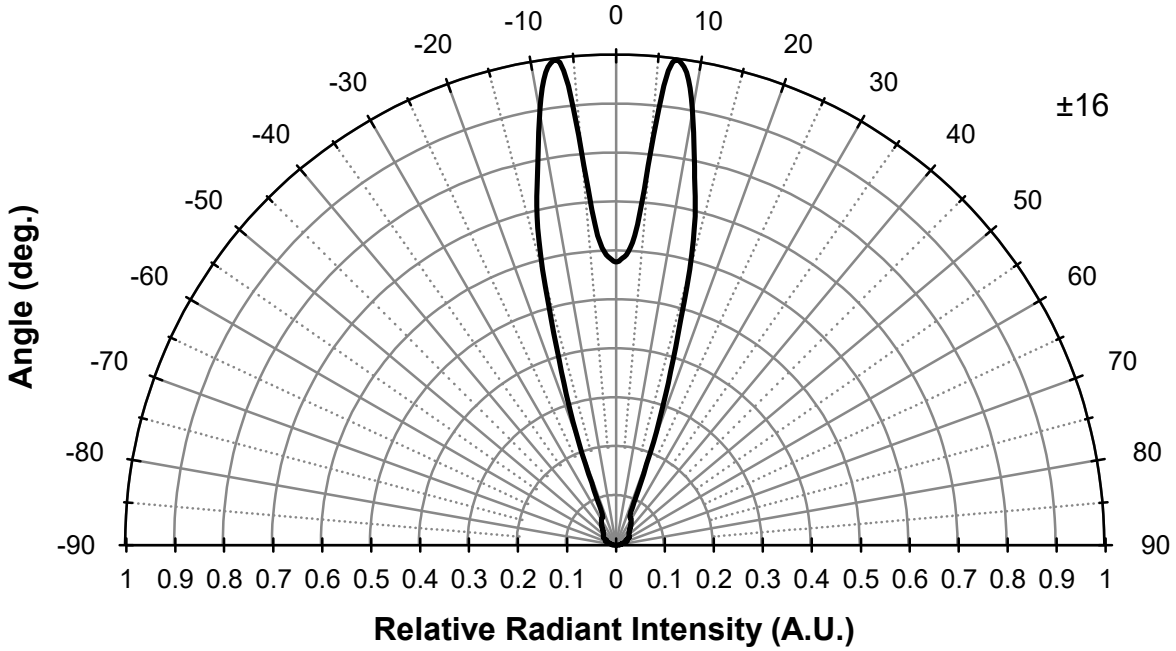
Relative Spectral Emission



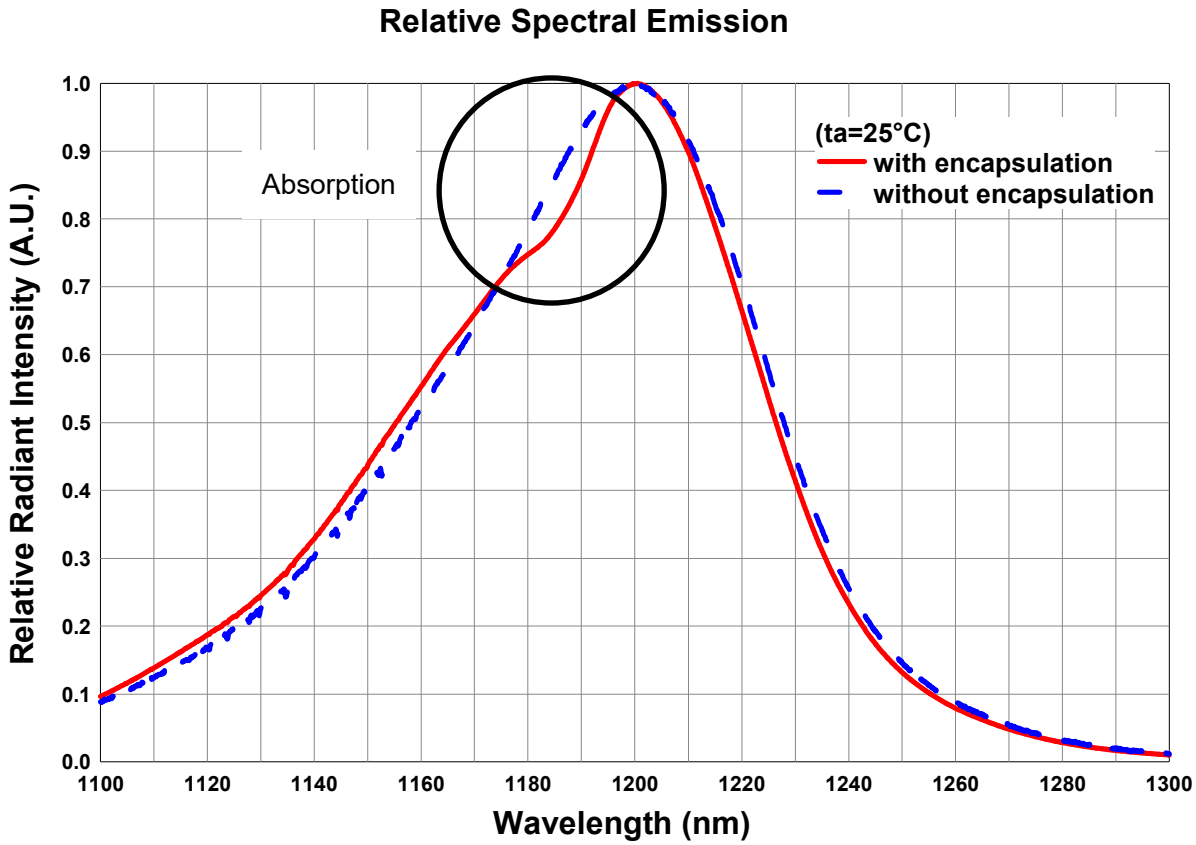
Radiation Characteristics



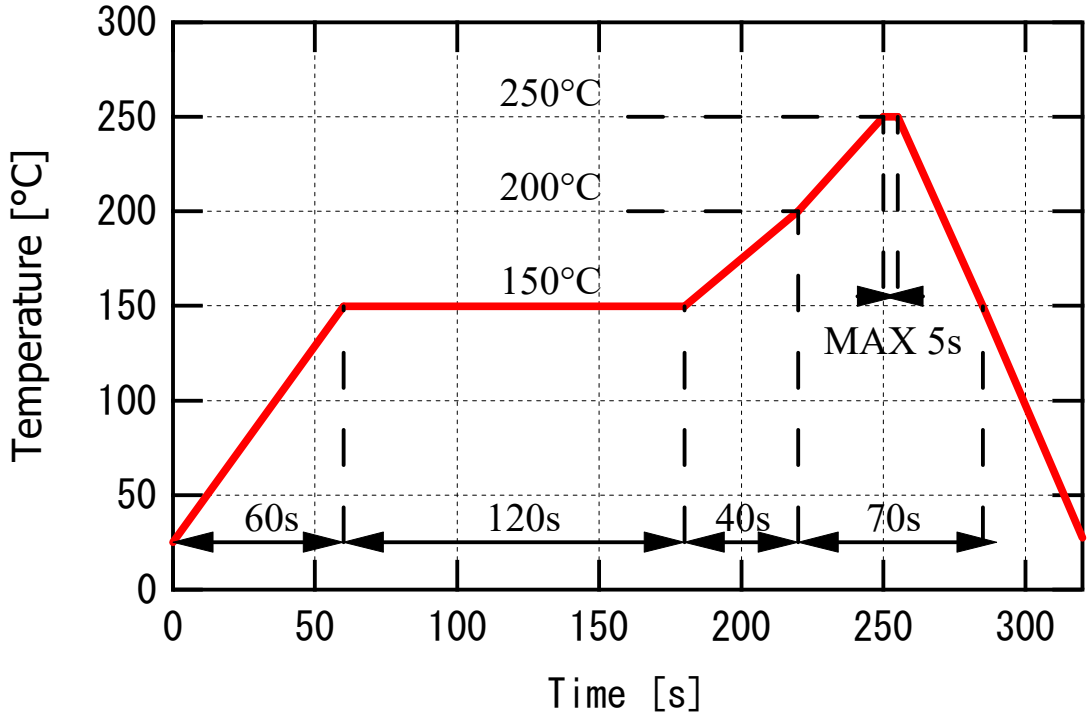
Radiation Characteristics



*The absorption of lens resin changes spectral emission.



Recommended Reflow Soldering Profile



Wrapping

Moisture barrier bag aluminum laminated film with a desiccant to keep out the moisture absorption during the transportation and storage.

SMD LED storage and handling precautions

Storage Conditions before Opening a Moisture-Barrier Aluminum Bag

- Before opening a moisture-barrier aluminum bag, please store it at <30ºC, <60%RH.
- Please note that the maximum shelf life is 12 months under these conditions.

Storage Conditions after Opening a Moisture-Barrier Aluminum Bag

- After opening a moisture-barrier aluminum bag, store the aluminum bag and silica gel in a desiccator.
- After opening the bag, please solder the LEDs within 72 hours in a room with 5 - 30ºC, <50%RH.
- Please put any unused, remaining LEDs and silica gel back in the same aluminum bag and then vacuum-seal the bag.
- It is recommended to keep the re-sealed bag in a desiccator at <30%RH.
- The 72-hour- long floor life does not include the time while LEDs are stored in the moisture-barrier aluminum bag. However, we strongly recommend to solder the LEDs as soon as possible after opening the aluminum bag.

Notes about Re-sealing a Moisture-Barrier Aluminum Bag

- When vacuum-sealing an opened aluminum bag, if you find the moisture-indicator of the silica gel has changed to pink from blue (indicating a relative humidity of 30 % or more), please do not use the unused LEDs, the aluminum bag, or the silica gel.

Notes about Opening a Re-sealed Moisture-Barrier Aluminum Bag

- When opening a vacuumed and re-sealed aluminum bag in order to use the remaining LEDs stored in the bag, if you find that the moisture-indicator of the silica has changed to pink, please do not use the LEDs.

Disclaimer

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Product data and parameters in this catalog are typical values based on reasonably up-to-date measurements. Product data and parameters may vary by user application and over time.

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